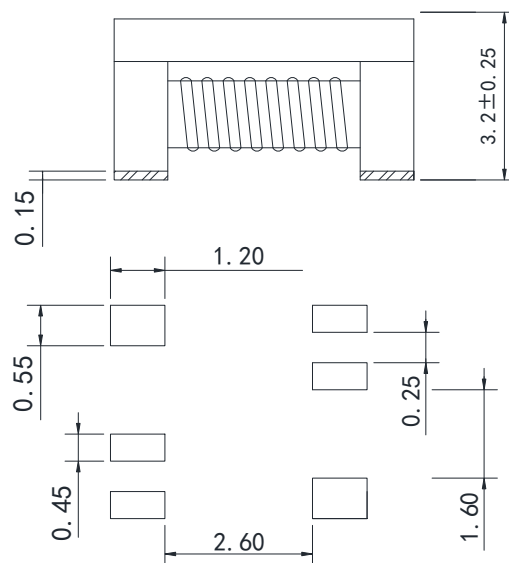
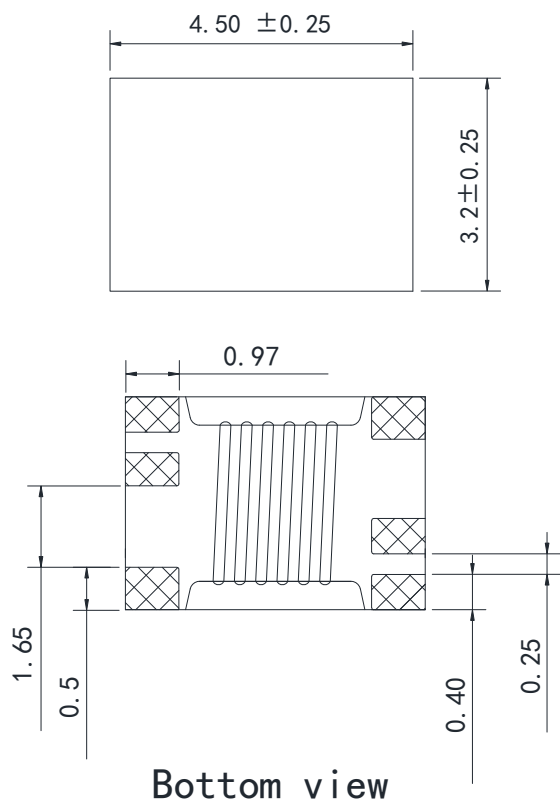




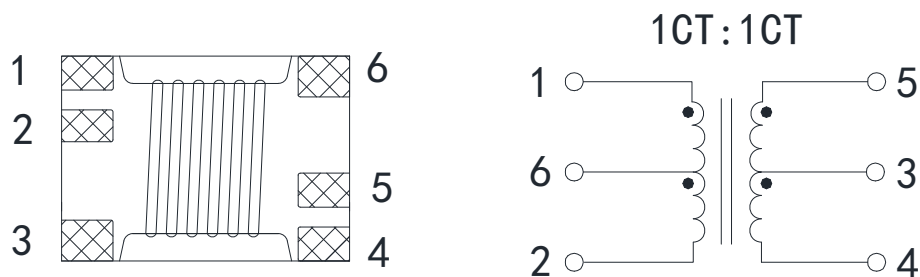
SMD CHIP LAN

T*4532-SERIES

1. Dimension (mm):



2. SCHEMATIC DIAGRAM:





CHIP LAN

T*4532-SERIES

3. ELECTRICAL SPECIFICATIONS:

rate standard POE Rating	Part Number	TR	OCL	Cww	DCR	Insertion Loss	Return Loss	HI-POT
		20KHz, 0.1V	100KHz,0.1V	100KHz,0 .1V	@25°C	SDD21	SDD11	Vrms 1mA
		1-2 :5-4	1-2 ,5-4	1-2 To 5- 4	1-2, 5-4	1-2 To 5-4	1-2 To 5-4	1-2 To 5-4
1G Base-T NON Poe	TG4532- 351-B	1CT:1CT ±5%	350uH Min with 8mA DC Bias	35pF Max	4.0Ω Max	-1.5dB Max@1-100MHz	-16dB Min@1-100MHz	1500
1G Base-T 60W Poe	TG4532- 181-B	1CT:1CT ±5%	180uH Min with 8mA DC Bias	35pF Max	4.0Ω Max	-1.5dB Max@1-100MHz	-16dB Min@1-100MHz	1500
1G Base-T 60W Poe	TG4532- 201P60-B	1CT:1CT ±5%	200uH Min with 8mA DC Bias	35pF Max	3.0Ω Max	-1.5dB Max@1-100MHz	-16dB Min@1-100MHz	1500
2.5G Base-T 60W Poe	TF4532- 181P60-B	1CT:1CT ±5%	180uH Min with 8mA DC Bias	35pF Max	1.6Ω Max	-1.0dB Max@1-100MHz -1.5dB Max @100-150MHz	-16dB Min@1-100MHz -14dB Min @100-150MHz	1500
5G Base-T 60W Poe	TD4532- 181P60-B	1CT:1CT ±5%	180uH Min with 8mA DC Bias	35pF Max	1.6Ω Max	-1.0dB Max@1-100MHz -1.5dB Max @100150MHz -2.0dB Max @150-250MHz	-16dB Min@1-100MHz -14dB Min @100-150MHz 12dB Min @150-250MHz	1500
10G Base-T 60W Poe	TN4532- 121P60-B	1CT:1CT ±5%	120uH Min with 8mA DC Bias	35pF Max	1.2Ω Max	-1.0dB Max@1-100MHz -1.5dB Max @100-250MHz -2.0dB Max @250-500MHz	-20dB Min@1-100MHz -14dB Min @100-250MHz -12dB Min @250-500MHz	1500

- * Meets IEEE 802.3ab bz an Standards, Supports 1G-10G base-t transmission rate applications.
- * Meets IEEE 802.3bt Standards, 0-1050mA current capability, Supports 0-90W PoE applications.
- * Operating Temperature Range: -40°C to +85°C and -40°C to +125°C.
- * RoHS Compliant
- * Storage temp.: -10°C ~ +40°C R.H.: 65% Max.
- * Moisture sensitivity level (MSL) 2 (1 year floor life at < 30°C/65% relative humidity).



CHIP LAN

T*4532-SERIES

4. IR REFLOW 是依 IPC/JEDEC J-STD-020D.1 的規範:

Phase 1 - Pre-Heat(预热)

During the Pre-Heat phase, the solder paste dries and its more volatile ingredients evaporate. The component body temperature should be brought at a controlled rate from room temperature (approximately 25°C) to $175 \pm 25^\circ\text{C}$. The maximum rate of change of temperature during the Pre-Heat phase should be less than $+3^\circ\text{C/s}$ to avoid component damage due to thermal stress.

Phase 2 - Flux Activation(熔融)

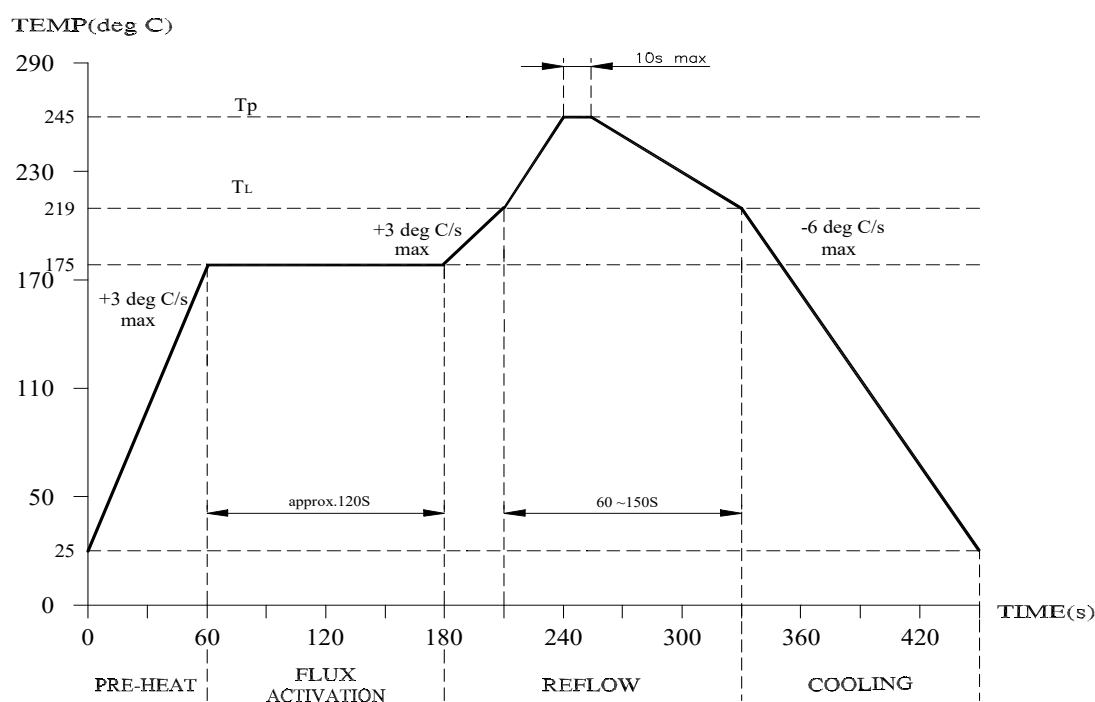
During the Flux Activation phase the flux component of the solder paste has time to micro-each and clean the metallized pads and component leads in preparation for solder reflow. The component body temperature should be maintained at $175 \pm 25^\circ\text{C}$ for 60~180s.

Phase 3 - Reflow(回流)

During the reflow phase the component lead temperature is brought to above the melting point of the solder alloy in use and held long enough to ensure complete wetting of all surfaces. For the industry norm solder alloy Sn96.5 Ag3.0 Cu0.5 this melting temperature is 219°C . The component lead temperature should be maintained above 219°C for 60 to 150s. The maximum rate of change of temperature during the reflow phase should be less than $+3^\circ\text{C/s}$ to avoid component damage due to thermal stress. The maximum component body lead temperature promised for TAG SMT devices during the reflow phase is 245°C for less than 10s.

Phase 4 - Cooling(冷却)

During the cooling phase the molten solder connections are allowed to slowly re-solidify into strong solder fillets. A fast cooling rate reduces the grain size of the inter-metallic compounds and strengthens the solder joints. However, due to the risk of thermal shock and solder joint brittleness, the maximum rate of change of temperature during the cooling phase should be less than -6°C/s .



COMPONENT BODY REFLOW TEMPERATURE PROFILE

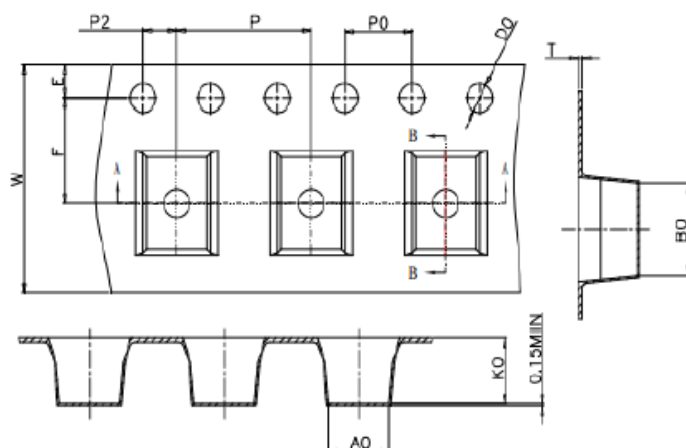


CHIP LAN

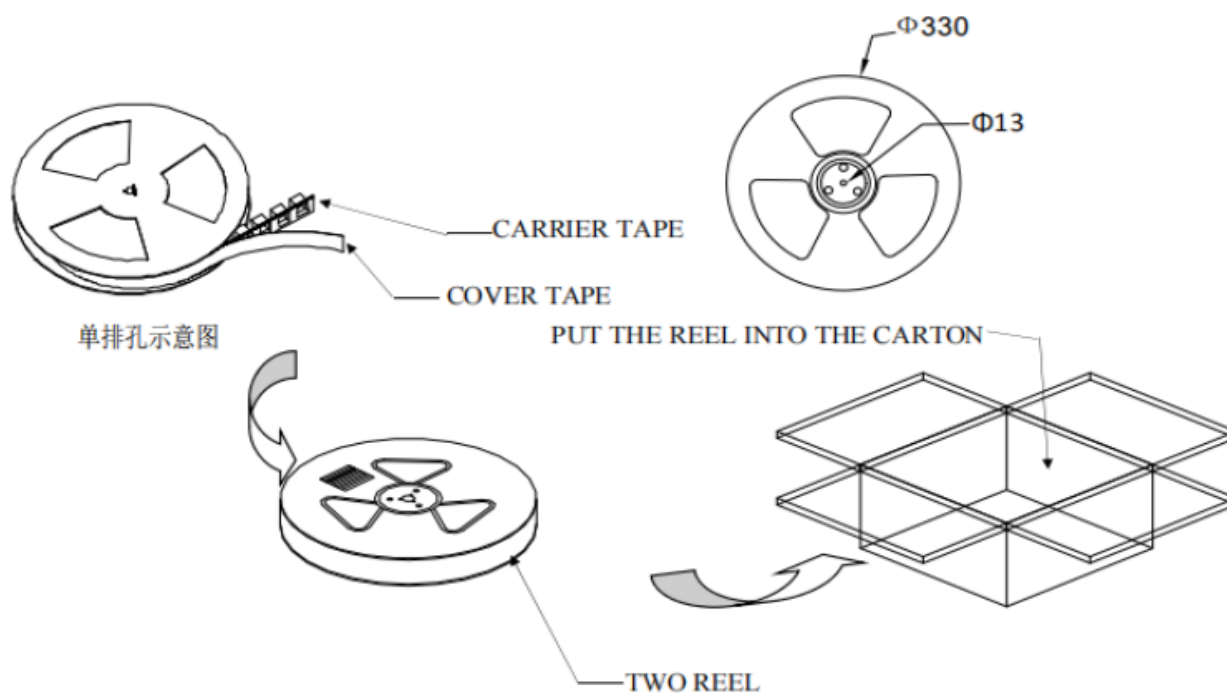
T*4532-SERIES

5. Package Information:

reel and Tape dimensions(unit: mm):



W	12.00±0.30	P	8.00±0.10	A0	3.60±0.10
E	1.75±0.10	P0	4.00±0.10	B0	4.90±0.10
F	5.50±0.10	P2	2.00±0.10	D0	1.50 ^{+0.10} _{0.00}
T	0.35±0.05	K0	3.50±0.10		



Package quantity:

One Reel: 2000 Pcs